TOSHIBA 2SK2965

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

2 S K 2 9 6 5

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS SWITCHING REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

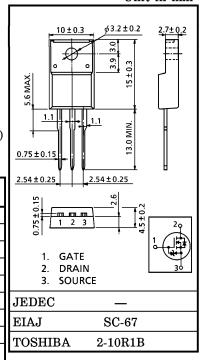
Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.15 \Omega$ (Typ.)

- High Forward Transfer Admittance : $|Y_{fs}| = 10 \text{ S}$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 200 \,\text{V}$)
- Enhancement-Mode : $V_{th} = 1.5 \sim 3.5 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$ m v_{DSS}$	200	V	
Drain-Gate Voltage (RG	${ m v_{DGR}}$	200	V	
Gate-Source Voltage	v_{GSS}	± 20	V	
Drain Current	DC	$I_{\mathbf{D}}$	11	A
	Pulse	I_{DP}	33	A
Drain Power Dissipation	$P_{\mathbf{D}}$	35	W	
Single Pulse Avalanche	EAS	115	mJ	
Avalanche Current	I_{AR}	11	A	
Repetitive Avalanche Er	E_{AR}	3.5	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	$^{\circ}\mathrm{C}$	

INDUSTRIAL APPLICATIONS Unit in mm



THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th (ch-c)}	3.57	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	62.5	°C/W

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** V_{DD} = 50 V, Starting T_{ch} = 25°C, L = 1.53 mH, R_{G} = 25 Ω , I_{AR} = 11 A

This transistor is an electrostatic sensitive device. Please handle with caution.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	IGSS	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	_	_	±10	μ A
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μ A
Gate-Source Breakdown Voltage		V (BR) DSS	$I_D = 10 \text{ mA}, \text{ V}_{GS} = 0 \text{ V}$	200	_	_	V
Gate Thresho	ld Voltage	$V_{ m th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.5	_	3.5	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$	_	0.15	0.26	Ω
Forward Tran	sfer Admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 5.5 \text{ A}$	5.0	10	_	S
Input Capacitance		C_{iss}	V-~ - 10 V V~~ - 0 V	_	1200	_	pF
Reverse Transfer Capacitance		C_{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz	_	100	_	
Output Capacitance		Coss		_	290	_	
Switching Time	Rise Time	t _r	$V_{GS} \stackrel{10 \text{ V}}{_{0 \text{ V}}} \stackrel{\text{I}_{D} = 5.5 \text{ A}}{_{0 \text{ V}}} \stackrel{\text{V}_{OUT}}{_{0 \text{ RL}}} \stackrel{\text{RL}}{_{18 \Omega}} = 180 \text{ V}$	_	15	_	
	Turn-on Time	ton		_	25	_	
	Fall Time	tf		_	10	_	ns
	Turn-off Time	t _{off}	$V_{\mathrm{IN}}: t_{\mathrm{r}}, t_{\mathrm{f}} < 5 \mathrm{ns}, \ \mathrm{Duty} \leq 1\%, t_{\mathrm{W}} = 10 \mu \mathrm{s}$	_	75	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$Q_{ m g}$	$V_{DD} = 100 \text{ V}, V_{GS} = 10 \text{ V}$	_	30	_	C
Gate-Source Charge		$Q_{ m gs}$	$I_{\mathrm{D}} = 10 \mathrm{A}$	_	20	_	nC
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$			10	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	11	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	33	A
Diode Forward Voltage	$ m v_{DSF}$	$I_{DR} = 11 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-2.0	V
Reverse Recovery Time	t_{rr}	$I_{DR} = 11 \text{ A}, V_{GS} = 0 \text{ V}$	_	175	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 100 A/\mu s$	_	1.3	_	μ C

MARKING

